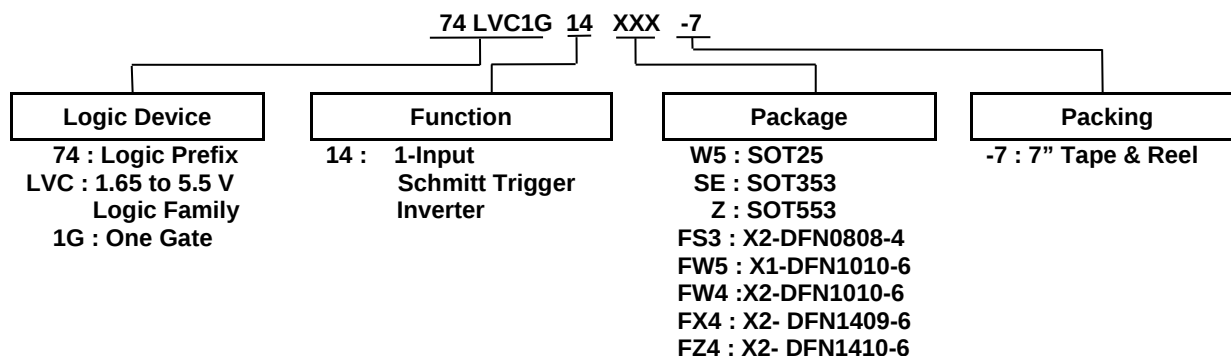


Ordering Information



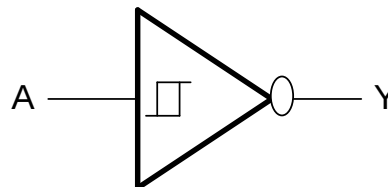
Device	Package Code	Package (Notes 4 & 5)	Package Size	7" Tape and Reel	
				Quantity	Part Number Suffix
74LVC1G14W5-7	W5	SOT25	3.0mm × 2.8mm × 1.2mm 0.95mm Lead Pitch	3000/Tape & Reel	-7
74LVC1G14SE-7	SE	SOT353	2.0mm × 2.0mm × 1.1mm 0.65mm Lead Pitch	3000/Tape & Reel	-7
74LVC1G14Z-7	SE	SOT553	1.6mm × 1.6 mm × 0.62mm 0.5mm Lead Pitch	4000/Tape & Reel	-7
74LVC1G14FS3-7	FS3	X2-DFN0808-4	0.9mm × 0.9 mm × 0.35mm 0.5mm Pad Pitch (Diamond)	5000/Tape & Reel	-7
74LVC1G14FW5-7 (Future Product)	FW5	X1-DFN1010-6 (Future Product)	1.0mm × 1.0mm × 0.5mm 0.35mm Pad Pitch	5000/Tape & Reel	-7
74LVC1G14FW4-7	FW4	X2-DFN1010-6	1.0mm × 1.0mm × 0.4mm 0.35mm Pad Pitch	5000/Tape & Reel	-7
74LVC1G14FX4-7	FX4	X2-DFN1409-6 (Chip Scale Alternative)	1.4mm × 0.9mm × 0.4mm 0.5mm Pad Pitch	5000/Tape & Reel	-7
74LVC1G14FZ4-7	FZ4	X2-DFN1410-6	1.4mm × 1.0mm × 0.4mm 0.5mm Pad Pitch	5000/Tape & Reel	-7

Notes: 4. Pad layout as shown on Diodes' suggested pad layout, which can be found on our website at <http://www.diodes.com/package-outlines.html>.
 5. The taping orientation is located on our website at <https://www.diodes.com/assets/Diodes-Packaging/ap02007.pdf>.

Pin Descriptions

Pin Name	Description
A	Data Input
GND	Ground
Y	Data Output
Vcc	Supply Voltage

Logic Diagram



Function Table

Inputs	Output
A	Y
H	L
L	H

Absolute Maximum Ratings (Notes 6, 7)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD MM	Machine Model ESD Protection	200	V
V _{CC}	Supply Voltage Range	-0.5 to 6.5	V
V _I	Input Voltage Range	-0.5 to 6.5	V
V _O	Voltage Applied to Output in High Impedance or I _{OFF} State	-0.5 to 6.5	V
V _O	Voltage Applied to Output in High or Low State	-0.5 to V _{CC} +0.5	V
I _{IK}	Input Clamp Current V _I < 0	-50	mA
I _{OK}	Output Clamp Current	-50	mA
I _O	Continuous Output Current	±50	mA
I _{CC} , I _{GND}	Continuous Current Through V _{CC} or GND	±100	mA
T _J	Operating Junction Temperature	-40 to 150	°C
T _{STG}	Storage Temperature	-65 to 150	°C

Notes: 6. Stresses beyond the Absolute Maximum Ratings may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.
7. Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range..

Recommended Operating Conditions (Note 8)

Symbol	Parameter		Min	Max	Unit
V _{CC}	Operating Voltage	Operating	1.65	5.5	V
		Data Retention Only	1.5	—	V
V _I	Input Voltage		0	5.5	V
V _O	Output Voltage		0	V _{CC}	V
I _{OH}	High-Level Output Current	V _{CC} = 1.65V	—	-4	mA
		V _{CC} = 2.3V	—	-8	
		V _{CC} = 2.7V	—	-12	
		V _{CC} = 3V	—	-16	
			—	-24	
		V _{CC} = 4.5V	—	-32	
I _{OL}	Low-Level Output Current	V _{CC} = 1.65V	—	4	mA
		V _{CC} = 2.3V	—	8	
		V _{CC} = 2.7V	—	12	
		V _{CC} = 3V	—	16	
			—	24	
		V _{CC} = 4.5V	—	32	
T _A	Operating Free-Air Temperature	—	-40	+125	°C

Note: 8. Unused inputs should be held at V_{CC} or Ground.

Electrical Characteristics (@T_A = -40°C to +85°C. All typical values are at V_{CC} = 3.3V, T_A = +25°C)

Symbol	Parameter	Test Conditions	V _{CC}	Min	Typ.	Max	Unit
V _{T+}	Positive-Going Input Threshold Voltage	—	1.65V	0.70	—	1.20	—
		—	2.3V	1.11	—	1.60	—
		—	3V	1.50	—	2.00	—
		—	4.5V	2.16	—	2.74	—
		—	5.5V	2.61	—	3.33	—
V _{T-}	Negative- Going Input Threshold Voltage	—	1.65V	0.30	—	0.72	—
		—	2.3V	0.58	—	1.00	—
		—	3V	0.80	—	1.30	—
		—	4.5V	1.21	—	1.95	—
		—	5.5V	1.45	—	2.35	—
ΔV _T	Hysteresis (V _{T+} - V _{T-})	—	1.65V	0.30	—	0.62	—
		—	2.3V	0.40	—	0.80	—
		—	3V	0.35	—	1.00	—
		—	4.5V	0.55	—	1.10	—
		—	5.5V	0.60	—	1.20	—
V _{OH}	High Level Output Voltage	I _{OH} = -100μA	1.65V to 5.5V	V _{CC} - 0.1	—	—	V
		I _{OH} = -4mA	1.65V	1.2	—	—	
		I _{OH} = -8mA	2.3V	1.9	—	—	
		I _{OH} = -12mA	2.7V	2.2	—	—	
		I _{OH} = -16mA	3V	2.4	—	—	
		I _{OH} = -24mA		2.3	—	—	
		I _{OH} = -32mA	4.5V	3.8	—	—	
V _{OL}	Low-Level Output Voltage	I _{OL} = 100μA	1.65V to 5.5V	—	—	0.1	V
		I _{OL} = 4mA	1.65V	—	—	0.45	
		I _{OL} = 8mA	2.3V	—	—	0.3	
		I _{OL} = 12mA	2.7V	—	—	0.4	
		I _{OL} = 16mA	3V	—	—	0.4	
		I _{OL} = 24mA		—	—	0.55	
		I _{OL} = 32mA	4.5	—	—	0.55	
I _I	Input Current	V _I = 5.5 V or GND	0 to 5.5V	—	—	± 5	μA
I _{OFF}	Power Down Leakage Current	V _I or V _O = 5.5V	0	—	—	± 10	μA
I _{CC}	Supply Current	V _I = 5.5V of GND I _O = 0	1.65V to 5.5V	—	—	10	μA
ΔI _{CC}	Additional Supply Current	Input at V _{CC} - 0.6V	3V to 5.5V	—	—	500	μA

Electrical Characteristics (continued) (@T_A = -40°C to +125°C. All typical values are at V_{CC} = 3.3V, T_A = +25°C)

Symbol	Parameter	Test Conditions	V _{CC}	Min	Typ.	Max	Unit
V _{T+}	Positive- Going Input Threshold Voltage	—	1.65V	0.70	—	1.20	—
		—	2.3V	1.11	—	1.60	—
		—	3V	1.50	—	2.00	—
		—	4.5V	2.16	—	2.74	—
		—	5.5V	2.61	—	3.33	—
V _{T-}	Negative- Going Input Threshold Voltage	—	1.65V	0.30	—	0.75	—
		—	2.3V	0.58	—	1.03	—
		—	3V	0.80	—	1.33	—
		—	4.5V	1.21	—	1.95	—
		—	5.5V	1.45	—	2.35	—
ΔV _T	Hysteresis (V _{T+} - V _{T-})	—	1.65V	0.30	—	0.62	—
		—	2.3V	0.37	—	0.80	—
		—	3V	0.32	—	1.00	—
		—	4.5V	0.50	—	1.20	—
		—	5.5V	0.55	—	1.40	—
V _{OH}	High Level Output Voltage	I _{OH} = -100μA	1.65V to 5.5V	V _{CC} - 0.1	—	—	V
		I _{OH} = -4mA	1.65V	0.95	—	—	
		I _{OH} = -8mA	2.3V	1.7	—	—	
		I _{OH} = -12mA	2.7V	1.9	—	—	
		I _{OH} = -16mA	3V	1.9	—	—	
		I _{OH} = -24mA		2.0	—	—	
		I _{OH} = -32mA	4.5V	3.4	—	—	
V _{OL}	Low-Level Output Voltage	I _{OL} = 100μA	1.65V to 5.5V	—	—	0.1	V
		I _{OL} = 4mA	1.65V	—	—	0.7	
		I _{OL} = 8mA	2.3V	—	—	0.45	
		I _{OL} = 12mA	2.7V	—	—	0.6	
		I _{OL} = 16mA	3V	—	—	0.6	
		I _{OL} = 24mA		—	—	0.8	
		I _{OL} = 32mA	4.5V	—	—	0.8	
I _I	Input Current	V _I = 5.5V or GND	0 to 5.5V	—	—	± 100	μA
I _{OFF}	Power Down Leakage Current	V _I or V _O = 5.5V	0	—	—	± 200	μA
I _{CC}	Supply Current	V _I = 5.5V of GND I _O = 0	1.65V to 5.5V	—	—	200	μA
ΔI _{CC}	Additional Supply Current	Input at V _{CC} - 0.6V	3V to 5.5V	—	—	5000	μA

Package Characteristics (All typical values are at $V_{CC} = 3.3V$, $T_A = +25^{\circ}C$)

Symbol	Parameter	Test Conditions	V_{CC}	Min	Typ.	Max	Unit
θ_{JA}	Thermal Resistance Junction-to-Ambient	SOT25	(Note 9)	—	204	—	$^{\circ}C/W$
		SOT353		—	371	—	
		SOT553		—	231	—	
		X2-DFN0808-4		—	400	—	
		X1-DFN1010-6		—	435	—	
		X2-DFN1010-6		—	445	—	
		X2-DFN1409-6		—	470	—	
		X2-DFN1410-6		—	460	—	
θ_{JC}	Thermal Resistance Junction-to-Case	SOT25	(Note 9)	—	52	—	$^{\circ}C/W$
		SOT353		—	143	—	
		SOT553		—	105	—	
		X2-DFN0808-4		—	225	—	
		X1-DFN1010-6		—	250	—	
		X2-DFN1010-6		—	250	—	
		X2-DFN1409-6		—	275	—	
		X2-DFN1410-6		—	265	—	

Note: 9. Test condition for each of the 8 package types: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

Switching Characteristics

$T_A = -40^{\circ}C$ to $+85^{\circ}C$, $C_L = 15pF$ as noted (see Figure 1)

Parameter	From Input	To Output	$V_{CC} = 1.8V$ $\pm 0.15V$		$V_{CC} = 2.5V$ $\pm 0.2V$		$V_{CC} = 3.3V$ $\pm 0.3V$		$V_{CC} = 5V$ $\pm 0.5V$		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{pd}	A	Y	1.0	9.9	0.7	5.5	0.7	4.6	0.7	4.4	ns

$T_A = -40^{\circ}C$ to $+85^{\circ}C$, $C_L = 30$ or $50pF$ as noted (See Figure 2)

Parameter	From Input	To Output	$V_{CC} = 1.8V$ $\pm 0.15V$		$V_{CC} = 2.5V$ $\pm 0.2V$		$V_{CC} = 3.3V$ $\pm 0.3V$		$V_{CC} = 5V$ $\pm 0.5V$		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{pd}	A	Y	1.0	11	0.7	6.5	0.7	5.5	0.7	5	ns

$T_A = -40^{\circ}C$ to $+125^{\circ}C$, $C_L = 15pF$ as noted (See Figure 1)

Parameter	From Input	To Output	$V_{CC} = 1.8V$ $\pm 0.15V$		$V_{CC} = 2.5V$ $\pm 0.2V$		$V_{CC} = 3.3V$ $\pm 0.3V$		$V_{CC} = 5V$ $\pm 0.5V$		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{pd}	A	Y	1.0	12.5	0.7	7.5	0.7	6.5	0.7	5.5	ns

$T_A = -40^{\circ}C$ to $+125^{\circ}C$, $C_L = 30$ or $50pF$ as noted (See Figure 2)

Parameter	From Input	To Output	$V_{CC} = 1.8V$ $\pm 0.15V$		$V_{CC} = 2.5V$ $\pm 0.2V$		$V_{CC} = 3.3V$ $\pm 0.3V$		$V_{CC} = 5V$ $\pm 0.5V$		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{pd}	A	Y	1.0	14.0	0.7	8.5	0.7	7.0	0.7	6.5	ns

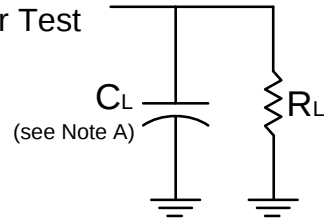
Operating Characteristics

$T_A = +25^\circ\text{C}$

Parameter		Test Conditions	$V_{CC} = 1.8\text{V}$	$V_{CC} = 2.5\text{V}$	$V_{CC} = 3.3\text{V}$	$V_{CC} = 5\text{V}$	Unit
			Typ.	Typ.	Typ.	Typ.	
C_{pd}	Power Dissipation Capacitance	$f = 10\text{ MHz}$	20	21	22	25	pF

Parameter Measurement Information

From Output
Under Test



V_{CC}	Inputs		V_M	C_L	R_L
	V_I	t_r/t_f			
$1.8\text{V} \pm 0.15\text{V}$	V_{CC}	$\leq 2\text{ns}$	$V_{CC}/2$	15pF	1M Ω
$2.5\text{V} \pm 0.2\text{V}$	V_{CC}	$\leq 2\text{ns}$	$V_{CC}/2$	15pF	1M Ω
$3.3\text{V} \pm 0.3\text{V}$	3V	$\leq 2.5\text{ns}$	1.5V	15pF	1M Ω
$5\text{V} \pm 0.5\text{V}$	V_{CC}	$\leq 2.5\text{ns}$	$V_{CC}/2$	15pF	1M Ω

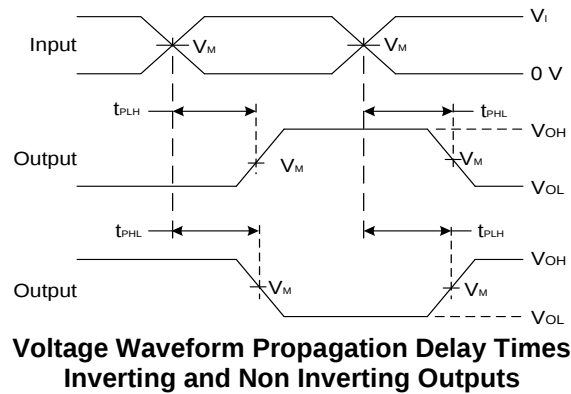
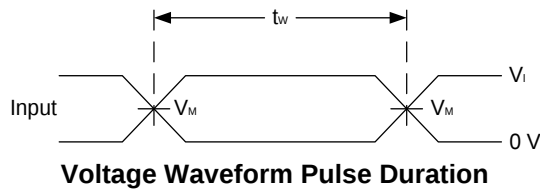
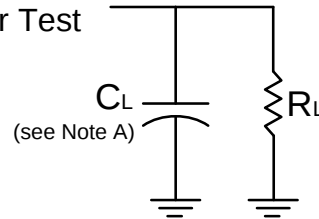


Figure 1. Load Circuit and Voltage Waveforms

- Notes:
- A. Includes test lead and test apparatus capacitance.
 - B. All pulses are supplied at pulse repetition rate $\leq 10\text{MHz}$.
 - C. Inputs are measured separately one transition per measurement.
 - D. t_{PLH} and t_{PHL} are the same as t_{PD} .

Parameter Measurement Information (continued)

From Output
Under Test



V_{CC}	Inputs		V_M	C_L	R_L
	V_I	t_r/t_f			
$1.8V \pm 0.15V$	V_{CC}	$\leq 2ns$	$V_{CC}/2$	30pF	1k Ω
$2.5V \pm 0.2V$	V_{CC}	$\leq 2ns$	$V_{CC}/2$	30pF	500 Ω
$3.3V \pm 0.3V$	3V	$\leq 2.5ns$	1.5V	50pF	500 Ω
$5V \pm 0.5V$	V_{CC}	$\leq 2.5ns$	$V_{CC}/2$	50pF	500 Ω

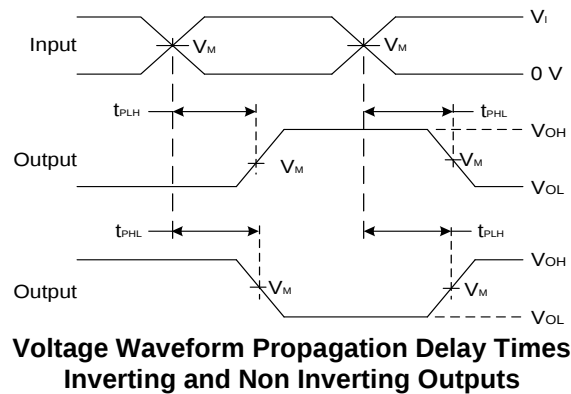
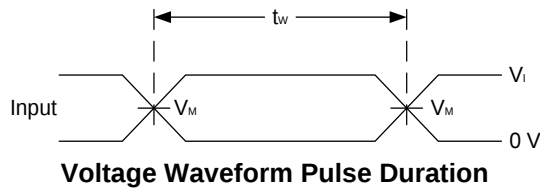
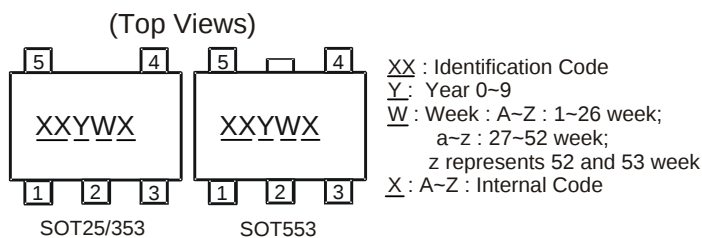


Figure 2. Load Circuit and Voltage Waveforms

- Notes:
- A. Includes test lead and test apparatus capacitance.
 - B. All pulses are supplied at pulse repetition rate $\leq 10MHz$.
 - C. Inputs are measured separately one transition per measurement.
 - D. t_{PLH} and t_{PHL} are the same as t_{PD} .

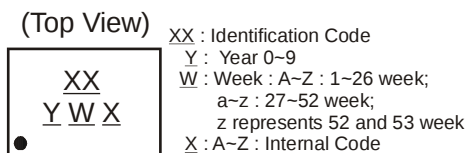
Marking Information

(1) SOT25, SOT353, and SOT553



Part Number	Package	Identification Code
74LVC1G14W5-7	SOT25	UP
74LVC1G14SE-7	SOT353	UP
74LVC1G14Z-7	SOT553	UP

(2) DFN Packages

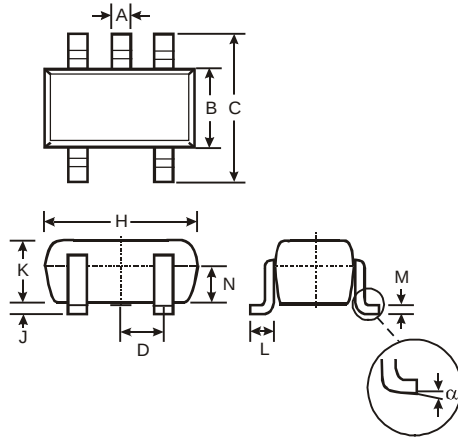


Part Number	Package	Identification Code
74LVC1G14FS3-7	X2-DFN0808-4	WP
74LVC1G14FW5-7	X1-DFN1010-6	V8
74LVC1G14FW4-7	X2-DFN1010-6	UP
74LVC1G14FX4-7	X2-DFN1409-6	MG
74LVC1G14FZ4-7	X2-DFN1410-6	UP

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

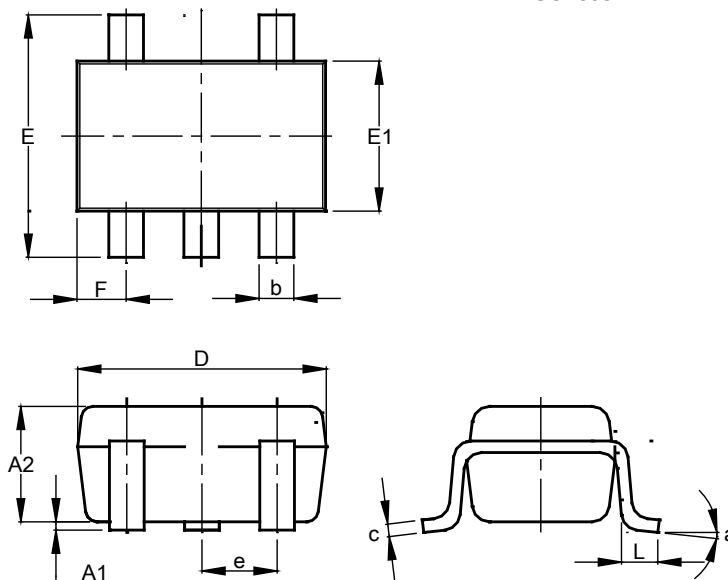
(1) Package Type: SOT25



SOT25			
Dim	Min	Max	Typ
A	0.35	0.50	0.38
B	1.50	1.70	1.60
C	2.70	3.00	2.80
D	—	—	0.95
H	2.90	3.10	3.00
J	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
M	0.10	0.20	0.15
N	0.70	0.80	0.75
a	0°	8°	—
All Dimensions in mm			

(2) Package Type: SOT353

SOT353

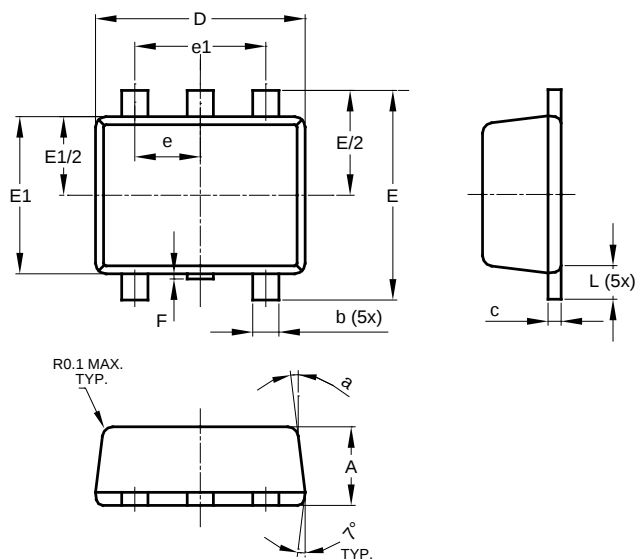


SOT353			
Dim	Min	Max	Typ
A1	0.00	0.10	0.05
A2	0.90	1.00	0.95
b	0.10	0.30	0.25
c	0.10	0.22	0.11
D	1.80	2.20	2.15
E	2.00	2.20	2.10
E1	1.15	1.35	1.30
e	0.650 BSC		
F	0.40	0.45	0.425
L	0.25	0.40	0.30
a	0°	8°	—
All Dimensions in mm			

Package Outline Dimensions (continued)

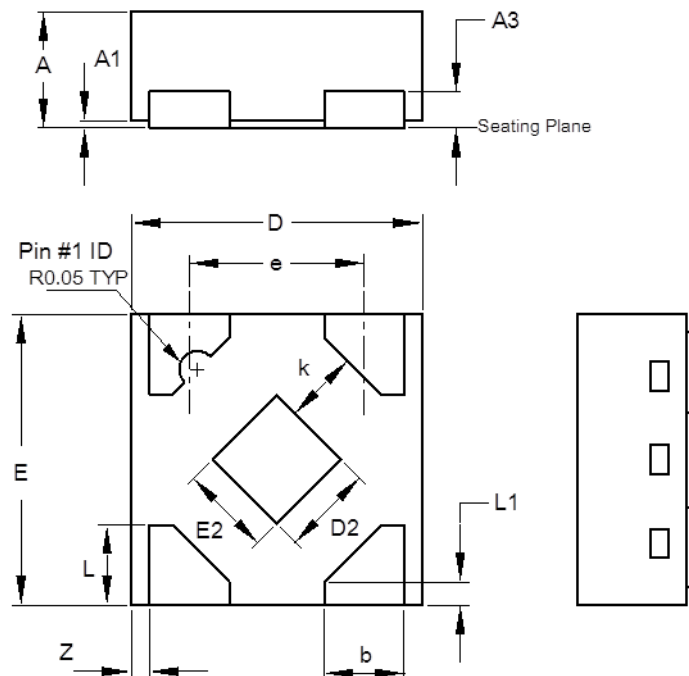
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

(3) Package Type: SOT553



SOT553			
Dim	Min	Max	Typ
A	0.55	0.62	0.60
b	0.15	0.30	0.20
c	0.10	0.18	0.15
D	1.50	1.70	1.60
E	1.55	1.70	1.60
E1	1.10	1.25	1.20
e	0.50 BSC		
e1	1.00 BSC		
F	0.00	0.10	—
L	0.10	0.30	0.20
a	6°	8°	7°
All Dimensions in mm			

(4) Package Type X2-DFN0808-4



X2-DFN0808-4			
Dim	Min	Max	Typ
A	0.25	0.35	0.30
A1	0	0.04	0.02
A3	-	-	0.13
b	0.17	0.27	0.22
D	0.75	0.85	0.80
D2	0.15	0.35	0.25
E	0.75	0.85	0.80
E2	0.15	0.35	0.25
e	-	-	0.48
k	0.20	-	-
L	0.17	0.27	0.22
L1	0.02	0.12	0.07
z	-	-	0.05
All Dimensions in mm			

Package Outline Dimensions (continued)

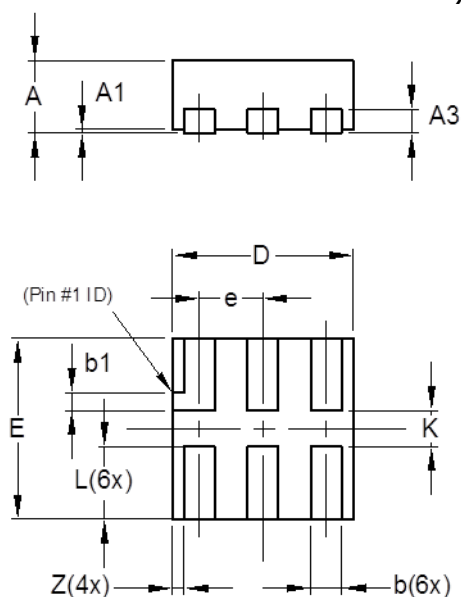
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

(5) Package Type: X1-DFN1010-6

(Future Product)

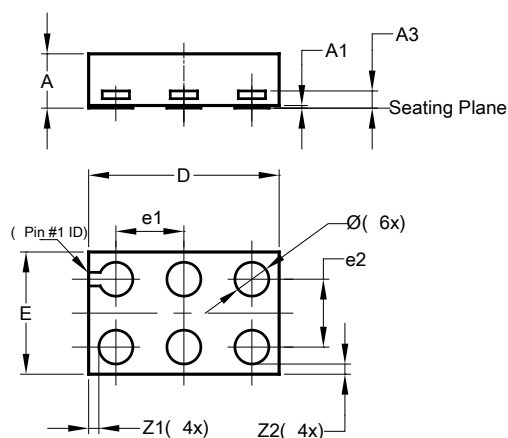
(6) Package Type: X2-DFN1010-6

X2-DFN1010-6



X2-DFN1010-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0.00	0.05	0.02
A3	—	—	0.13
b	0.14	0.20	0.17
b1	0.05	0.15	0.10
D	0.95	1.05	1.00
E	0.95	1.05	1.00
e	—	—	0.35
L	0.35	0.45	0.40
K	0.15	—	—
Z	—	—	0.065
All Dimensions in mm			

(7) Package Type: X2-DFN1409-6

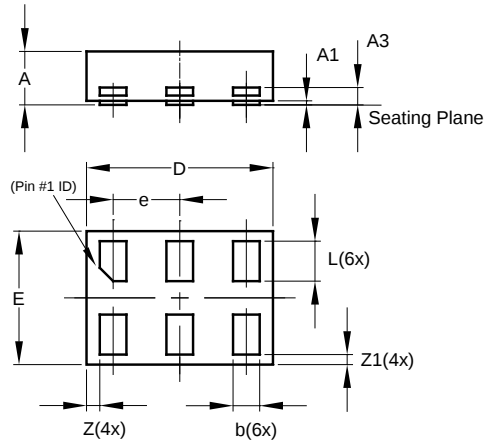


X2-DFN1409-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0	0.05	0.02
A3	—	—	0.13
Ø	0.20	0.30	0.25
D	1.35	1.45	1.40
E	0.85	0.95	0.90
e1	—	—	0.50
e2	—	—	0.50
Z1	—	—	0.075
Z2	—	—	0.075
All Dimensions in mm			

Package Outline Dimensions (continued)

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

(8) Package Type: X2-DFN1410-6

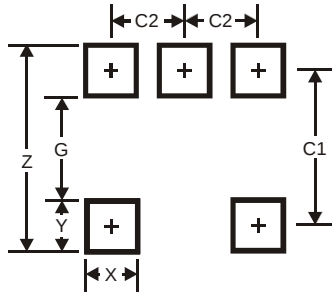


X2-DFN1410-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0.00	0.05	0.02
A3	—	—	0.13
b	0.15	0.25	0.20
D	1.35	1.45	1.40
E	0.95	1.05	1.00
e	—	—	0.50
L	0.25	0.35	0.30
Z	—	—	0.10
Z1	0.045	0.105	0.075
All Dimensions in mm			

Suggested Pad Layout

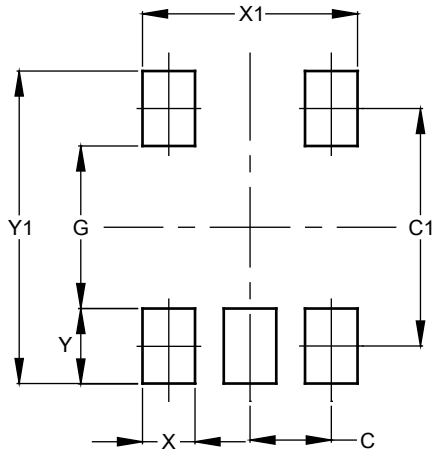
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

(1) Package Type: SOT25



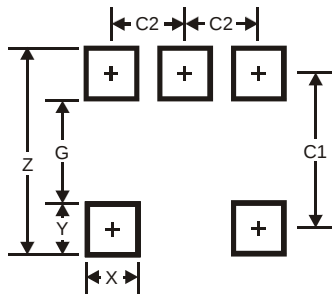
Dimensions	Value
Z	3.20
G	1.60
X	0.55
Y	0.80
C1	2.40
C2	0.95

(2) Package Type: SOT353



Dimensions	Value (in mm)
C	0.650
C1	1.900
G	1.300
X	0.420
X1	1.720
Y	0.600
Y1	2.500

(3) Package Type: SOT553

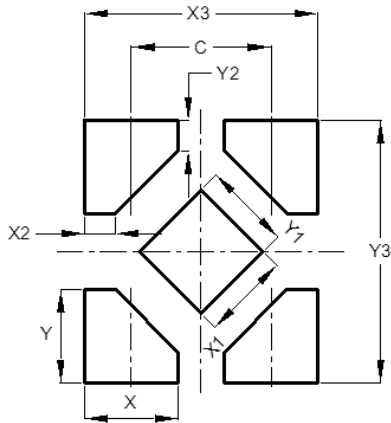


Dimensions	Value
Z	2.2
G	1.2
X	0.375
Y	0.5
C1	1.7
C2	0.5

Suggested Pad Layout (continued)

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

(4) Package Type X2-DFN0808-4

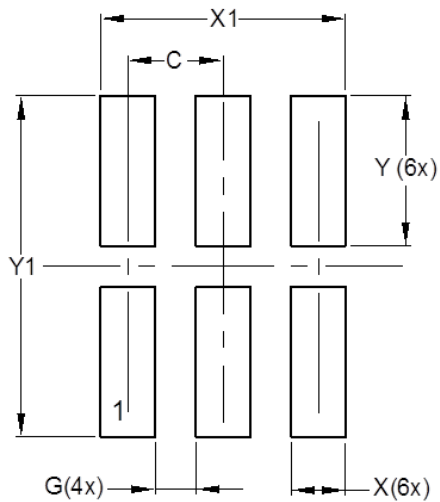


Dimensions	Value
C	0.480
X	0.320
X1	0.300
X2	0.106
X3	0.800
Y	0.320
Y1	0.300
Y2	0.106
Y3	0.900

(5) Package Type X1-DFN1010-6

(Future Product)

(6) Package Type X2-DFN1010-6

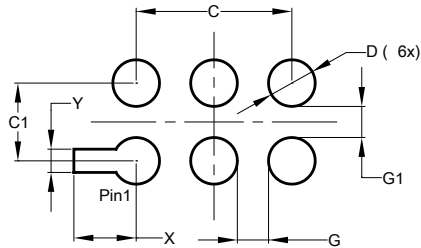


Dimensions	Value (in mm)
C	0.350
G	0.150
X	0.200
X1	0.900
Y	0.550
Y1	1.250

Suggested Pad Layout (continued)

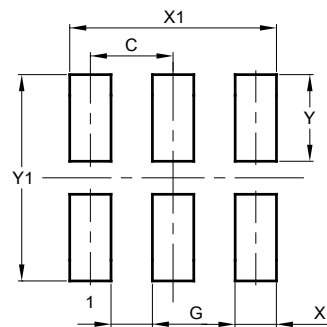
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

(7) Package Type: X2-DFN1409-6



Dimensions	Value (in mm)
C	1.000
C1	0.500
D	0.300
G	0.200
G1	0.200
X	0.400
Y	0.150

(8) Package Type: X2-DFN1410-6



Dimension s	Value (in mm)
C	0.500
G	0.250
X	0.250
X1	1.250
Y	0.525
Y1	1.250

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